

MOSFETs Silicon N-channel MOS (U-MOSIV)

# TK100F06K3

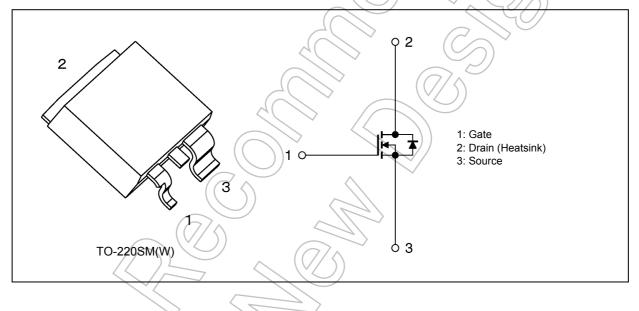
#### 1. Applications

- Switching Voltage Regulators
- DC-DC Converters
- · Motor Drivers

#### 2. Features

- (1) AEC-Q101 qualified
- (2) Low drain-source on-resistance:  $R_{DS(ON)} = 4.0 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (3) High forward transfer admittance:  $|Y_{fs}| = 174 \text{ S (typ.)}$
- (4) Low leakage current:  $I_{DSS}$  = 10  $\mu A$  (max) ( $V_{DS}$  = 60 V)
- (5) Enhancement mode:  $V_{th} = 3.0 \text{ to } 4.0 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA})$

### 3. Packaging and Internal Circuit



Start of commercial production



### 4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Charact	Symbol	Rating	Unit		
Drain-source voltage			$V_{DSS}$	60	V
Drain-gate voltage	$(R_{GS} = 20k\Omega)$		$V_{DGR}$	60	
Gate-source voltage			V <sub>GSS</sub> (	±20	
Drain current (DC)		(Note 1)	I <sub>D</sub>	100	Α
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	300	
Power dissipation	(T <sub>c</sub> = 25°C)		P <sub>D</sub>	180	W
Single-pulse avalanche energy		(Note 2)	EAS	81	mJ
Avalanche current		4	Jar	)) 100	Α
Repetitive avalanche energy		(Note 3)	E <sub>AR</sub>	18	mJ
Channel temperature		(Note 4)	(T <sub>ch</sub> )	175	°C
Storage temperature		(Note 4)	T <sub>stg</sub>	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

	Characteristics		Symbol	Max	Unit
Channel-to-case thermal resistance		<< ))	R <sub>th(ch-c)</sub>	0.83	°C/W

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 11  $\mu$ H,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 100 A

Note 3: Repetitive rating; pulse width limited by maximum channel temperature.

Note 4: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



#### 6. Electrical Characteristics

# 6.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V	7	_	10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	_	٧
Drain-source breakdown voltage (Note 5)	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	35	) /~	_	
Gate threshold voltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	3.0	/_	4.0	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 50 A	$\langle \rangle$	4.0	5.0	mΩ
Forward transfer admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 50 A	87	174		S

Note 5: If a reverse bias is applied between gate and source, this device enters V<sub>(BR)DSX</sub> mode. Note that the drain-source breakdown voltage is lowered in this mode.

# 6.2. Dynamic Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	1	4500	) —	pF
Reverse transfer capacitance	C <sub>rss</sub>			600	_	
Output capacitance	C <sub>oss</sub>			800	_	
Switching time (rise time)	t <sub>r</sub>	See Fig. 6.2.1	7,-11	18	_	ns
Switching time (turn-on time)	t <sub>on</sub>		$\bigcirc$ –	33		
Switching time (fall time)	t <sub>f</sub>		リー	23	_	
Switching time (turn-off time)	t <sub>off</sub>		_	73		

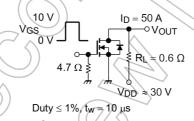


Fig. 6.2.1 Switching Time Test Circuit

### 6.3. Gate Charge Characteristics (Ta = 25°C unless otherwise specified)

Characteristics	Characteristics Symbol		Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	$Q_g$	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 100 \text{ A}$		98		nC
Gate-source charge	Q <sub>gs</sub>		_	57	_	
Gate-drain charge	$Q_{gd}$		_	41		

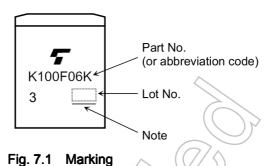
## 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (DC)	(Note 6)	I <sub>DR</sub>	_	_	_	100	Α
Reverse drain current (pulsed)	(Note 6)	I <sub>DRP</sub>	_	_	_	300	
Diode forward voltage		V <sub>DSF</sub>	I <sub>DR</sub> = 100 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V
Reverse recovery time		t <sub>rr</sub>	I <sub>DR</sub> = 100 A, V <sub>GS</sub> = 0 V	_	62	_	ns
Reverse recovery charge		Q <sub>rr</sub>	dl <sub>DR</sub> /dt = 50 A/μs	_	62	_	nC

Note 6: Ensure that the channel temperature does not exceed 175°C.



### 7. Marking (Note)



Note: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.





#### 8. Moisture-Proof Packing

This device is packed in a moisture-proof laminated aluminum bag.

#### 8.1. Precautions for Transportation and Storage (Note)

- (1) Avoid excessive vibration during transportation.
- (2) Do not toss or drop the packed devices to avoid ripping of the bag.
- (3) After opening the moisture-proof bag, the devices should be assembled within two weeks in an environment of 5°C to 30°C and RH70% or below. Perform reflow at most twice.
- (4) The moisture-proof bag may be stored unopened for up to 24 months at 5°C to 30°C and RH90% or below.
- (5) If, upon opening the bag, the moisture indicator card shows humidity of 30% or above (the color of the 30% dot has changed from blue to pink) or the expiration date has passed, the devices should be baked as follows:

Baking conditions: 125°C for 48 hours.

Note: Since the tape materials are not heat-proof, devices should be placed on either heat-proof trays or aluminum magazines when baking.

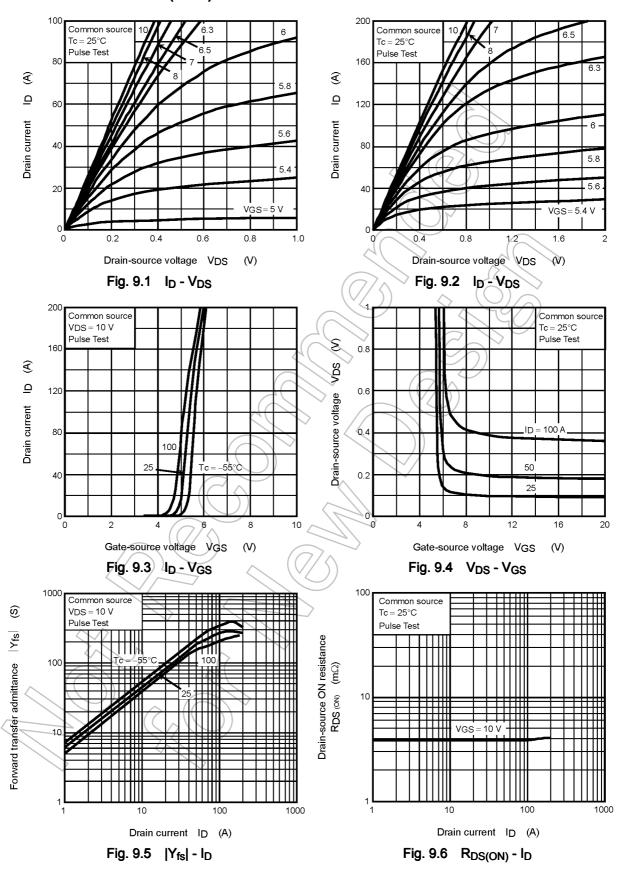


The humidity indicator shows an approximate ambient humidity at  $25\,^{\circ}\text{C}$ . If the ambient humidity is below  $30\,^{\circ}\text{M}$ , the color of all the indicator dots is blue. If, upon opening the bag, the color of the  $30\,^{\circ}\text{M}$  dot has changed from blue to pink, the devices should be baked before assembly.

Fig. 8.1.1 Humidity Indicator



### 9. Characteristics Curves (Note)





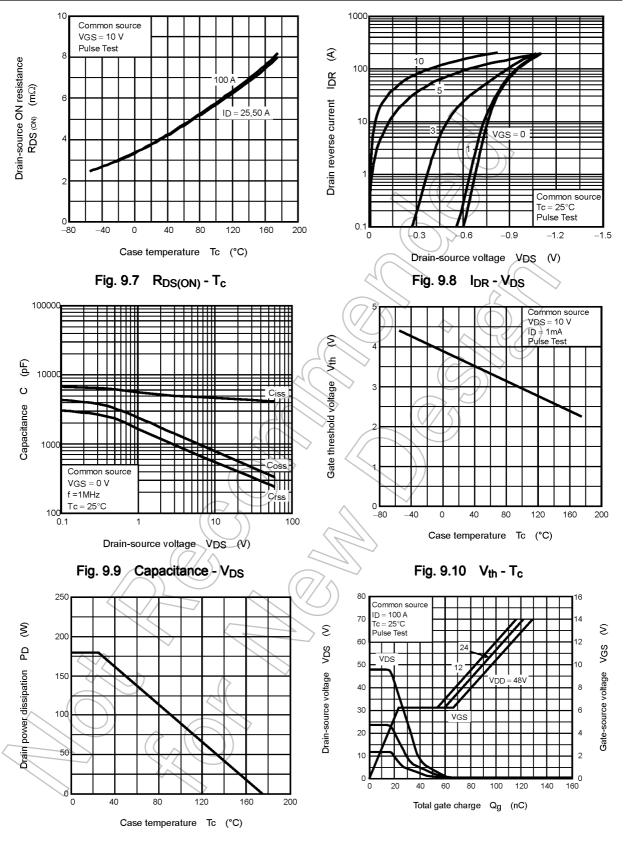


Fig. 9.11 P<sub>D</sub> - T<sub>c</sub> Fig. 9.12 Dynamic Input/Output Characteristics (Guaranteed Maximum)



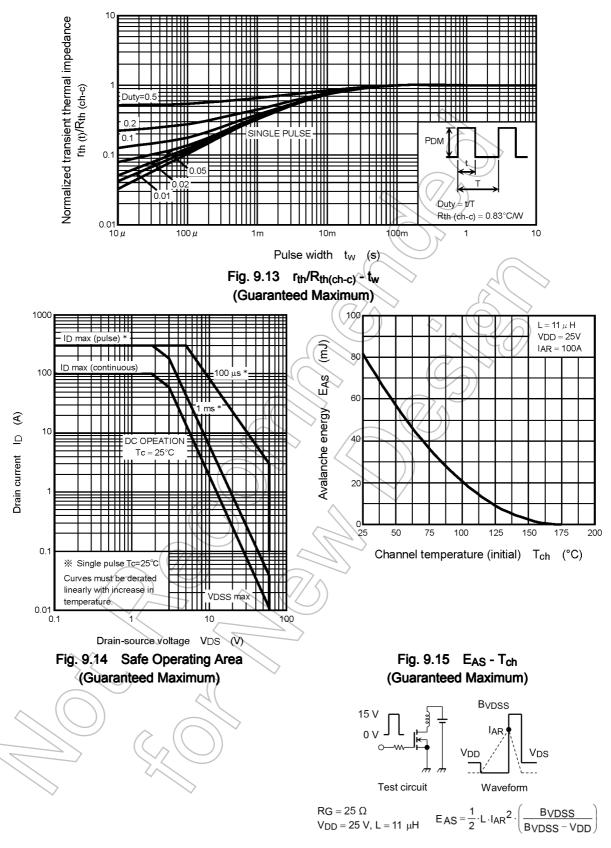


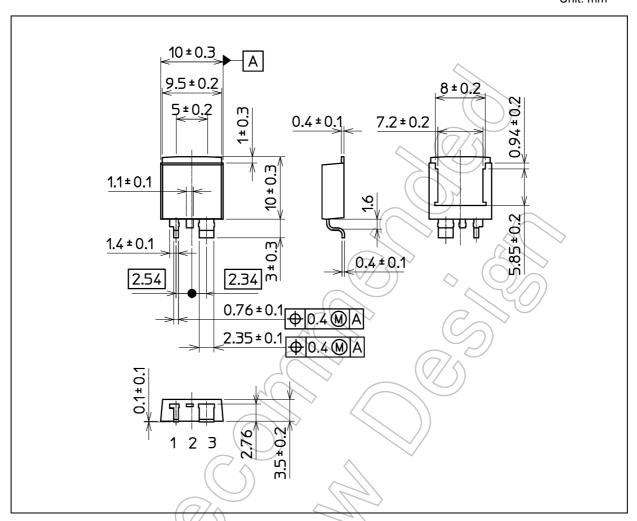
Fig. 9.16 Test Circuit/Waveform

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

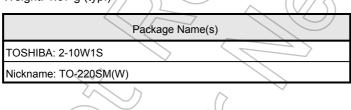


### **Package Dimensions**

Unit: mm



Weight: 1.07 g (typ.)





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